

## 2.5 x 2.0 x 0.8mm Clipped Sinewave Output

13MHz to 52MHz

- Ultra-miniature SMD package 2.5 x 2.0 x 0.8mm
- Stability from ±0.5ppm over -20° to +70°C
- Supply Voltage 1.8V, 2.5V or 3.0Volts
- Miniature, lightweight and compact
- Ideal for portable devices such as GPS and handsets





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### SPECIFICATION

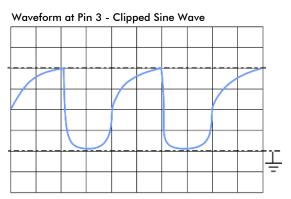
Product Series	M22S (Refer to VEM22S if voltage control function is required.)				
Output Wave Form:	Clipped Sine Wave				
Supply Voltage	1.8V±5% (1.71V ~ 1.89V)	2.5V±5% (2.37V ~ 2.62V)	3.0V±5% (2.85V ~ 3.15V)		
Frequency Range:	12.0MHz to 52.0MHz				
Initial Calibration Tolerance:	±2ppm maximum, +25°C, 1 hour after reflow				
Frequency Stability	From $\pm 0.5$ ppm to $\pm 2.5$ ppm over operating temperature range. Referenced to frequency reading at 25°C.				
vs Temperature: vs Ageing: vs Voltage Change: vs Load Change: vs Reflow:	±0.2ppm maximum for a ±5% voltage change ±0.2ppm maximum for a ±10% load change				
Output Voltage Level (Peak to peak):	0.8V p-p min., 2.0V p-p max. Load $10k\Omega//10pF \pm 10\%$				
Output Format:	DC coupled. See below for output waveform. Requires an external AC-Coupling capacitor at pin 3, 1000pF recommended.				
Current Consumption:	fo <26MHz: 2mA max. fo >26MHz: 2.5mA max.				
Startup Time:	2ms max. (to reach 90% amplitude and at 25°C±2°C)				
Packaging:	8.0mm tape; 4.0mm pitch; 180mm reel; 1000 pieces (code P1) or 3000 pieces (code P3) per reel. Cut tape for <1k pieces.				

## AVAILABLE FREQUENCY STABILITY vs OPERATING TEMPERATURE RANGE

Frequency S	tability (ppm)	±0.5	±1.0	±1.5	±2.0	±2.5
Temperature Range (°C)	0 ~ +50	✓	✓	✓	✓	✓
	-10 ~ +60	✓	✓	✓	✓	✓
	<b>-20</b> ~ +70	✓	✓	✓	✓	✓
	-30 ~ +75	ASK	✓	✓	✓	STD
	-40 ~ +85	ASK	ASK	✓	✓	✓

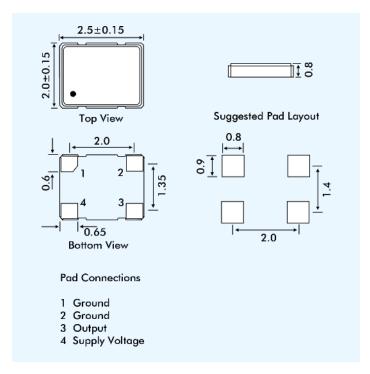
√ = available, STD = standard, ASK = call Technical Sales

#### **OUTPUT WAVEFORM**



Before AC-coupling capacitor

#### **EM22S - OUTLINES AND DIMENSIONS**





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#### **ENVIRONMENTAL PERFORMANCE SPECIFICATION**

Environmental Approvals:	RoHS Compliant, Pb (lead) free, Free of Cadmium, Hexavalent Chromium, Lead, Mercury, PBBs and PBDEs	
Moisture Sensitivity Test:	MSL = 1 per IPC/JEDEC J-STD-020D.1	
Humidity:	85% RH, 85°C, 48 hours	
Hermeticity, Fine Leak:	MIL-STD-883, method 1014, condition A	
Hermeticity, Gross Leak:	MIL-STD-883, method 1014, condition C	
Solderability:	MIL-STD-202F, method 208E	
Vibration:	MIL-STD-883, method 2007, condition A, 10~2000Hz 1.52mm 20g, each axis for 4 hours	
Mechanical Shock:	MIL-STD-883, method 2002, condition B, 1500g, 1/2 sine, 0.5ms, each axis 3 times	
Resistance to Solvent:	MIL-STD-202, method 215	
Resistance to Soldering Heat:	MIL-STD-202, method 210	
Temperature Cycling:	MIL-STD-883, method 1010	
Thermal Shock:	MIL-STD-883F, method 1011.9, Condition B -55~+125°C, 10 min soak time, 200 cycles	
H.A.S.T. (Highly Accelerated Stress Test):	JESD22-A110	
Storage Temperature Range:	-55° ∼ +125°C	
ESD Protection:	1.5kV min., human body model.	
Solder Pad Surface Finish:	Gold (Au) (0.3~1.0μm) over nickel (Ni) (1.27~8.89μm)	
Second Level Interconnect Category:	e4	
Unit Weight:	0.12gm	

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#### PART NUMBERING PROCEDURE

